

ABSTRACT

A method of laser processing for processing a laminated member where a metal thin film is protruded from an end portion of a silicon substrate at the bottom of the silicon substrate, wherein; a laser beam of which wavelength has the light absorption coefficient of the metal thin film being higher than the light absorption coefficient of the silicon substrate, is irradiated onto an boundary between an end of the silicon substrate and the metal thin film so as to cut the metal thin film.